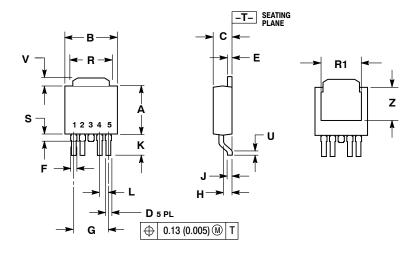




DPAK-5, CENTER LEAD CROP

CASE 175AA **ISSUE B**

DATE 15 MAY 2014

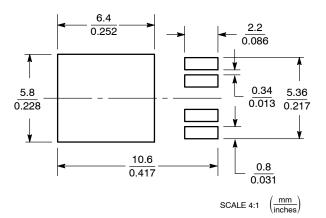


NOTES

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

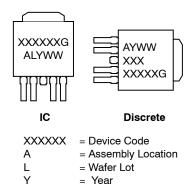
	INC	INCHES MILLIN		IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.235	0.245	5.97	6.22
В	0.250	0.265	6.35	6.73
С	0.086	0.094	2.19	2.38
D	0.020	0.028	0.51	0.71
Е	0.018	0.023	0.46	0.58
F	0.024	0.032	0.61	0.81
G	0.180	BSC	4.56 BSC	
Н	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.045	BSC	1.14 BSC	
R	0.170	0.190	4.32	4.83
R1	0.185	0.210	4.70	5.33
S	0.025	0.040	0.63	1.01
U	0.020		0.51	
٧	0.035	0.050	0.89	1.27
Z	0.155	0.170	3.93	4.32

RECOMMENDED SOLDERING FOOTPRINT*



^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAMS*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

= Work Week

= Pb-Free Package

WW

G

		Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DPAK-5 CENTER LEAD CROP		PAGE 1 OF 1	

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves brisefin and of 160 m are trademarked so defined values of services and of the confined values and of the values of the confined values and of the values of the confined values and of the values of the v special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.